

## 描述 / Descriptions

TO-252 塑封封装 双向可控硅。

Triac in a TO-252 Plastic Package.

## 特征 / Features

中电流可控硅，低通态压降，高可靠性和稳定性，热敏电阻特性低，无卤产品。

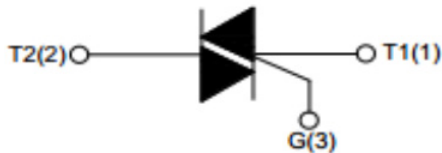
Medium current triac, Low on state voltage drop, High reliability and stability, Low thermal resistance, HF Product.

## 用途 / Applications

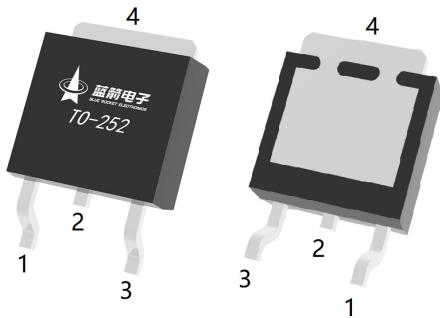
适用于一般用途交流开关。如固态继电器、加热调节、异步电动机起动电路、电机速度控制器等。

Suitable for general purpose AC switching .Such as static relays, heating regulation, induction motor starting circuits, motor speed controllers, etc.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN1 : Main Terminal 1    PIN 2、 4 : Main Terminal 2    PIN 3: Gate

## 印章代码 / Marking

见印章说明。

See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Repetitive peak off-state/reverse voltages(T <sub>j</sub> =125°C)	V <sub>DRM</sub> /V <sub>RPM</sub>	800	V
RMS on-state current(T <sub>C</sub> =110°C)	I <sub>T(RMS)</sub>	8	A
Non repetitive surge peak on-state current(full cycle, T <sub>j</sub> =25°C)	I <sub>TSM(t=20ms)</sub>	80	A
I <sup>2</sup> t value for fusing(T <sub>j</sub> =25°C)	I <sup>2</sup> t <sub>(tp=10ms)</sub>	32	A <sup>2</sup> s
Critical rate of rise of on-state current (I <sub>G</sub> =2I <sub>GT</sub> , f=120Hz T <sub>j</sub> =125°C)	dI/dt I-II-III	50	A/μs
Peak gate current(t <sub>p</sub> =20μs T <sub>j</sub> =125°C)	I <sub>GM</sub>	4.0	A
Average gate power dissipation(T <sub>j</sub> =125°C)	P <sub>G(AV)</sub>	1.0	W
Operating junction temperature range	T <sub>j</sub>	-40~125	°C
Storage junction temperature range	T <sub>stg</sub>	-40~150	°C
Junction to ambient(AC)	R <sub>th(j-a)</sub>	100	°C/W
Junction to case for(AC)	R <sub>th(j-c)</sub>	3.1	

**电性能参数 / Electrical Characteristics(Tj=25°C)**
**免缓冲器和逻辑电平 ( 3象限 ) / Snubberless and logic level ( 3 quadrants)**

符号 Symbol	测试条件 Test Conditions	信号区 Quadrant	数值 Value		单位 Unit
I <sub>GT</sub>	V <sub>D</sub> =12V R <sub>L</sub> =30Ω	I-II-III	Max.	10	mA
V <sub>GT</sub>	V <sub>D</sub> =12V R <sub>L</sub> =30Ω	I-II-III	Max.	1	V
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3KΩ T <sub>j</sub> =125°C	I-II-III	Min.	0.2	V
I <sub>L</sub>	I <sub>G</sub> =1.2I <sub>GT</sub>	I-III	Max.	25	mA
		II		30	
I <sub>H</sub>	I <sub>T</sub> =100mA		Max.	15	mA
(dV/dt)	V <sub>D</sub> =67% V <sub>DRM</sub> Gate Open	T <sub>j</sub> =125°C	Min.	40	V/μs
V <sub>TM</sub>	I <sub>TM</sub> =11A t <sub>p</sub> =380μs	T <sub>j</sub> =25°C	Max.	1.55	V
I <sub>DRM</sub>	V <sub>D</sub> =V <sub>DRM</sub> V <sub>R</sub> =V <sub>RPM</sub>	T <sub>j</sub> =25°C		5	μA
I <sub>RPM</sub>		T <sub>j</sub> =125°C		0.35	mA

电参数曲线图 / Electrical Characteristic Curve

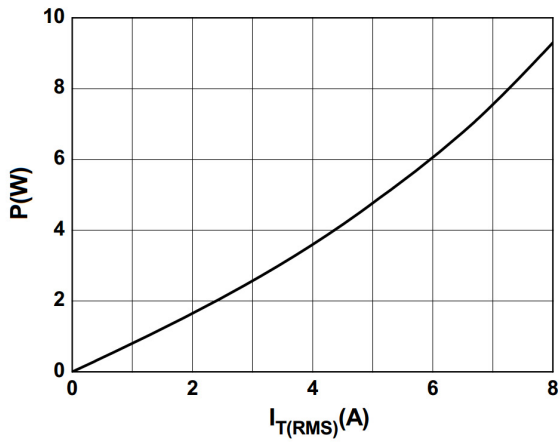


FIG.1 Maximum power dissipation versus RMS on-state current

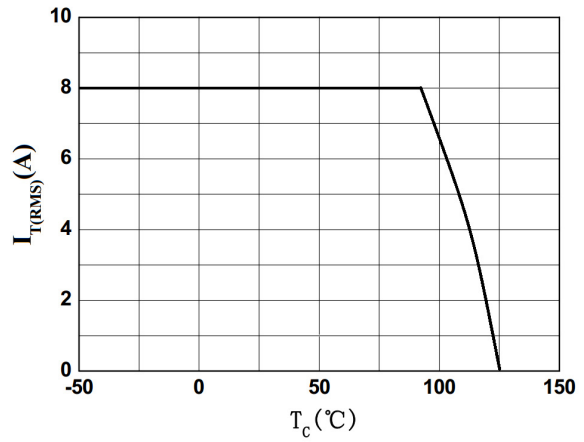


FIG.2: RMS on-state current versus case temperature

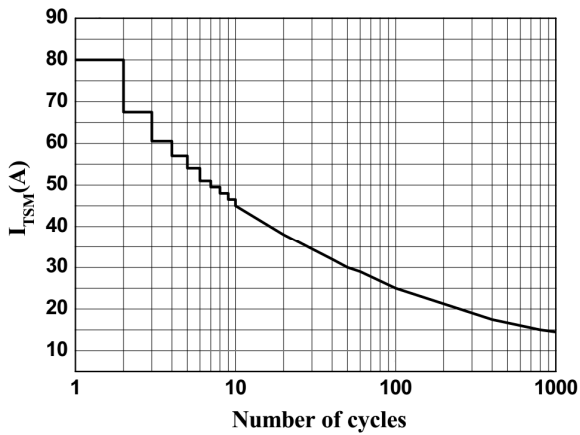


FIG.3: Surge peak on-state current versus number of cycles

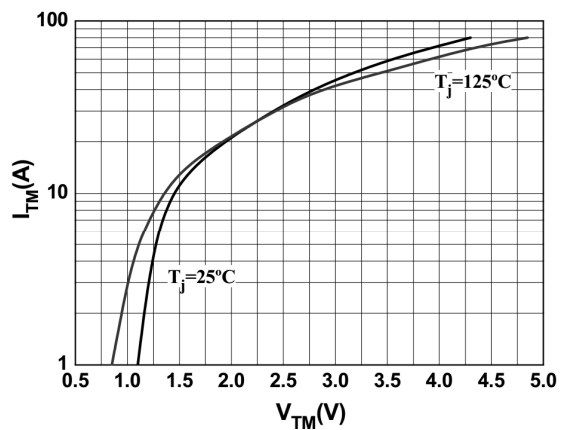


FIG.4: On-state characteristics

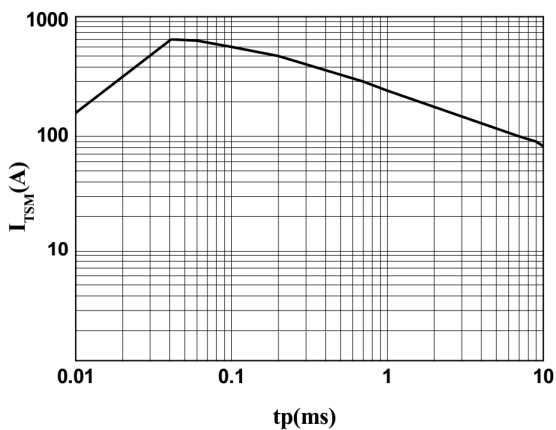


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 20\text{ms}$ , and corresponding value of  $I_2t$  ( $di/dt < 100\text{A}/\mu\text{s}$ )

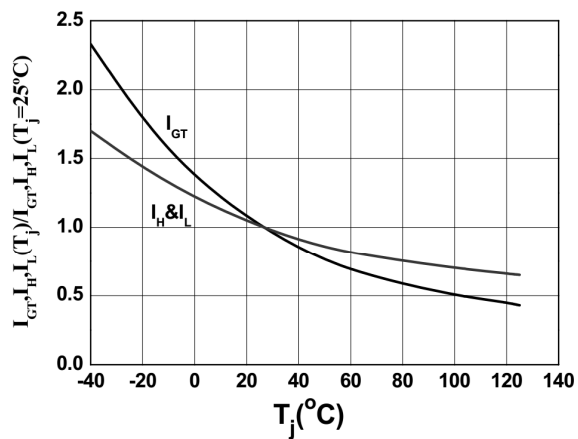
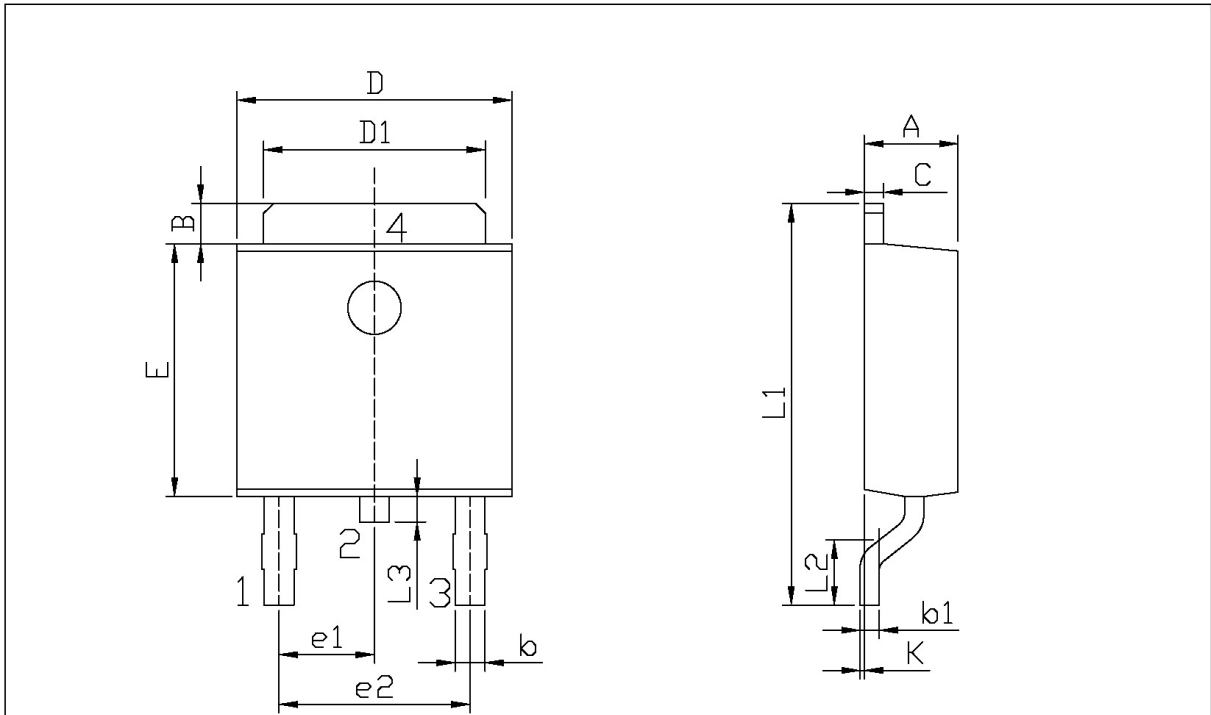


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

外形尺寸图 / Package Dimensions

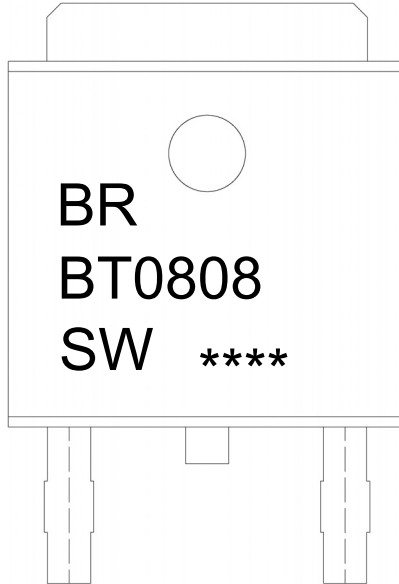


单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.50	0.90	e2	4.43	4.73
b1	0.45	0.55	L1	9.45	9.95
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

TO-252

印章说明 / Marking Instructions



说明：

BR： 为公司代码

BT0808： 为型号代码

SW： 为 I<sub>GT</sub> 分档代码

\*\*\*\*： 为生产批号代码，随生产批号变化

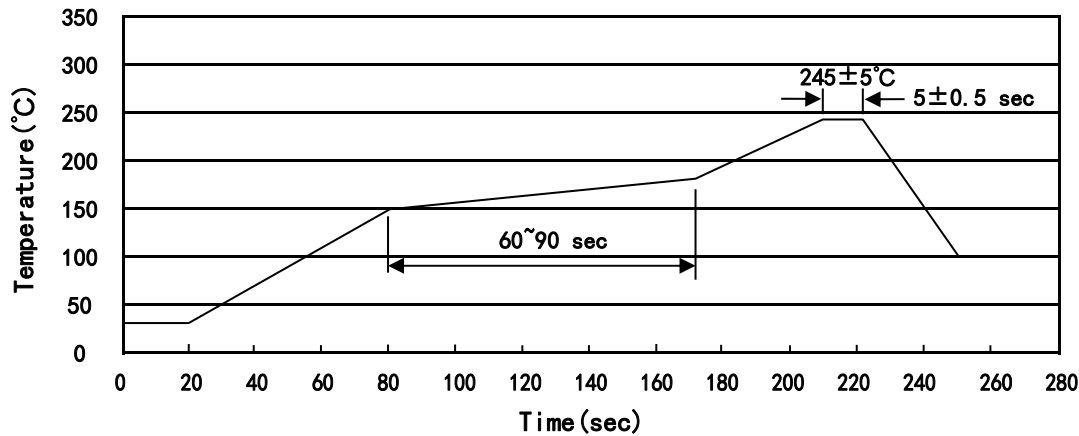
Note:

BR: Company Code

BT0808: Product Type Code

SW: I<sub>GT</sub> Bracket code

\*\*\*\*: Lot No. Code, code change with Lot No

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-252	2,500	2	5,000	6	30,000	13" ×16	360×360×50	380×335×366

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	575×290×180

**使用说明 / Notices**